

**REMARKS**

Claims 1, 2, 5-10, 17, 18 and 20-27 are pending in this application. By this Amendment, claims 1, 5 and 20 are amended, and claims 21-27 are added. The amendments and added claims introduce no new matter. Claims 4, 12 and 19 are canceled without prejudice to, or disclaimer of, the subject matter recited in those claims. Reconsideration of the application based on the above amendments and the following remarks is respectfully requested.

The Office Action objects to claim 20. The amendment to claim 20 obviates the objection. Reconsideration and withdrawal of the objection to claim 20 is respectfully requested.

The Office Action rejects claim 20 under 35 U.S.C. §103(a) over U.S. Patent No. 6,747,348 to Jeung et al. (hereinafter "Jeung") in view of U.S. Patent No. 6,445,069 to Ling et al. (hereinafter "Ling"); rejects claims 1, 4, 5, 12 and 17-20 under 35 U.S.C. §103(a) over U.S. Patent No. 6,750,547 to Jeung et al. (hereinafter "Jeung '547") in view of Ling and Jeung; rejects claims 6 and 7 under 35 U.S.C. §103(a) over Jeung '547 in view of Ling and Jeung and U.S. Patent No. 6,625,032 to Ito et al. (hereinafter "Ito"); and rejects claims 2 and 8-10 under 35 U.S.C. §103(a) over Jeung '547 in view of Ling, Jeung, Ito and JP-A-01-164044 (hereinafter "JP '044"). These rejections are respectfully traversed.

Without conceding the interpretation, or application, of the applied references, and solely to advance prosecution of this application, claims 1, 5 and 20 are amended to clarify relevant features. For example, claim 1 recites, among other features, a connecting layer that is disposed between the second surface of the chip component and the substrate, the connecting layer being formed in such a manner that the connecting layer and the insulating section are formed integrally. Claim 20 recites similar features.

The applied references do not teach, nor can they reasonably be considered to have suggested, such a combination of features. For example, the relied-upon Fig. 4L of Jeung, and Fig. 1G of Jeung '547, do not disclose a corresponding connecting layer with respect to the allegedly corresponding second surface and the substrate. The other references are not applied in a manner to overcome this shortfall in either Jeung or Jeung '547.

Additionally, claim 5 recites, among other features, mounting a chip component on an insulating adhesive in such a manner that the second surface faces the insulating adhesive with applying a compressive force between the substrate and the chip component so that the insulating adhesive has a first part and a second part, the first part being interposed between the chip component and the substrate, the second part being disposed adjacent to the chip component.

The applied references do not teach, nor can they reasonably be considered to have suggested, such a combination of features. For example, the method relating to relied-upon Fig. 1G of Jeung '547 does not disclose a corresponding mounting and applying of a compressive force between the substrate and the chip component so that the insulating adhesive has a first part and a second part, the first part being interposed between the chip component and the substrate, the second part being disposed adjacent to the chip component. The other references are not applied in a manner to overcome this shortfall in the application of Jeung '547 to the subject matter of claim 5.

Support for the amended features can be found, for example, on page 14, line 23 to page 15, line 6, and Fig. 7, element 62, of Applicant's disclosure, as filed.

For at least the above reasons, the applied references cannot reasonably be considered to have suggested that combinations of features positively recited in independent claims 1, 5 and 20. Additionally, claims 2, 6-10, 17 and 18 also would not have been reasonably suggested by the applied references for at least the respective dependence of these claims,

directly or indirectly, on an allowable base claim, as well as for the separately patentable subject matter that each of these claims recites.

Accordingly, reconsideration and withdrawal of the rejections of claims 1, 2, 5-10, 17, 18 and 20 over the variously applied references are respectfully requested.

Added claims 21-27 are likewise allowable at least for the respective dependence of these claims, directly or indirectly, on an allowable base claim, as well as for the separately patentable subject matter that each of these claims recites.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1, 2, 5-10, 17, 18 and 20-27 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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Attachment:

Request for Continued Examination

Date: March 5, 2008

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